

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Reissue Application of

PAI-HSIANG KAO, et al.

Patent No. 6,023,094

Issued: February 8, 2000

For: **SEMICONDUCTOR WAFER HAVING  
A BOTTOM SURFACE PROTECTIVE  
COATING**

**PRELIMINARY AMENDMENT**

400 Montgomery Street, Suite 1110  
San Francisco, CA 94104  
(415) 433-2250

Box Reissue  
Commissioner for Patents  
Washington, D.C. 20231

Sir:

Please amend the above-captioned reissue application as follows:

In the Claims

Please amend original Claim 1 as follows:

1. (Amended) A packaged integrated circuit device comprising:  
a die having a plurality of electrical [contacts] contact bumps disposed on a first surface of the die; and  
a protective film adhered directly to a back surface of the die, opposite the first surface, the protective film being thick enough to allow laser marking of the protective film without the laser penetrating to the die,  
wherein the protective film has a thickness between about 1.5 and 5 mils.

100223-1001

Please add the following new claims:

7. The packaged integrated circuit of Claim 1 wherein the protective film includes plastic.

8. The packaged integrated circuit of Claim 1 wherein the protective film includes epoxy.

9. The packaged integrated circuit of Claim 1 wherein the protective film includes laser identification markings.

10. The packaged integrated circuit of Claim 1 wherein the protective film is non-metallic.

11. A packaged integrated circuit device comprising:  
a die having a plurality of electrical contacts disposed on a first surface of the die; and  
a protective film adhered directly to a back surface of the die, opposite the first surface, the protective film being thick enough to allow laser marking of the protective film without the laser penetrating to the die,  
wherein the protective film has a thickness between about 1.5 and 5 mils and includes laser identification markings.

12. The packaged integrated circuit device of Claim 11 wherein the protective film includes epoxy.

13. The packaged integrated circuit device of Claim 11 wherein the protective film includes plastic.

14. The packaged integrated circuit device of Claim 11 wherein the protective film is substantially co-extensive with the back surface.

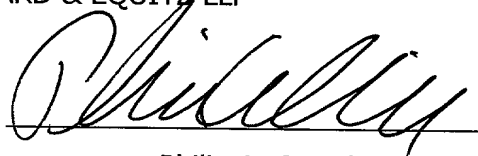
15. The packaged integrated circuit device of Claim 11 wherein the electrical contacts include a plurality of contact bumps.

Respectfully submitted,

GIRARD & EQUITZ LLP

Dated: 11/15/01

By:



Philip A. Girard  
Reg. No.28,848

Attorneys for Applicant(s)

Attorney Docket No. NSC1-G9900

10022583 44704  
TOTAL 682200